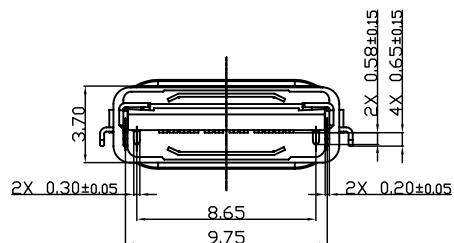
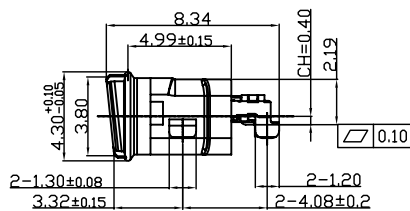
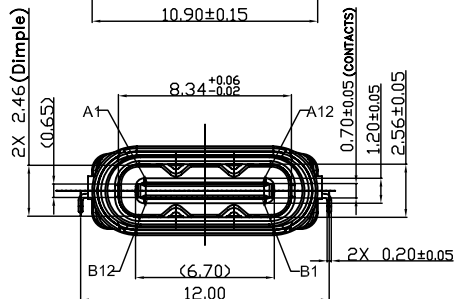
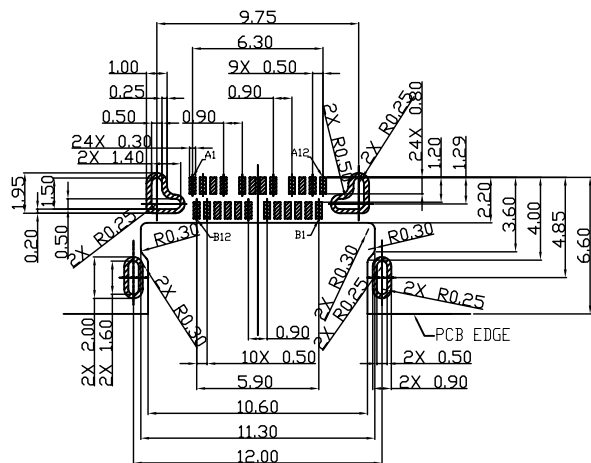


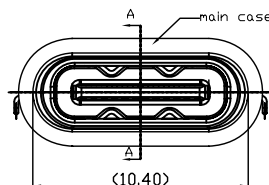
10	TOP	1	SILICA GEL	BLACK
4	SOLDER PIN	1	STAINLESS STEEL	SOLDER NICKEL: 50% MIN
8	SHELL BRASSING	1	PLA=TEMP. PLASTIC	BLACK
7	SHELL	1	STAINLESS STEEL	SOLDER NICKEL: 50% MIN
6	TOP TERMINAL	1	COPPER ALLOY	WATING SUE:25~26" 20 MIN;
5	BOTTOM TERMINAL	1	COPPER ALLOY	SOLDER TAIL:GOLD PLASL, 50% NICKEL OXIDRAL.
4	MID PLATE	1	STAINLESS STEEL	SOLDER NICKEL: 50% MIN
3	TIP BRASSING	1	PLA=TEMP. PLASTIC	BLACK
2	BOTTOM BRASSING	1	PLA=TEMP. PLASTIC	BLACK
1	MAIN BRASSING	1	PLA=TEMP. PLASTIC	BLACK
1100	DESCRIPTION	2/17	MATERIAL	FINISH



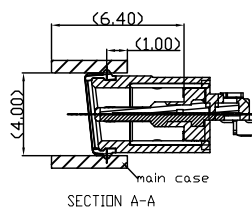
Pin No	Signal Name	Mating Sequence	Pin No	Signal Name	Mating Sequence
A1	GND	First	B12	GND	First
A2	TX1+	Second	B10	RX1+	Second
A3	TX1-	Second	B11	RX1-	Second
A4	Vbus	First	B9	Vbus	First
A5	CC1	Second	B8	SBU2	Second
A6	D+	Second	B7	D-	Second
A7	D-	Second	B6	D+	Second
A8	SBU1	Second	B5	CC2	Second
A9	Vbus	First	B4	Vbus	First
A10	RX2-	Second	B3	TX2-	Second
A11	RX2+	Second	B2	TX2+	Second
A12	GND	First	B1	GND	First
SHELL	GND		SHELL	GND	



RECOMMENDED PCB LAYOUT
(Tolerance=±0.05)



PANEL CUT-OUT REFERENCE



SECTION A-A

Notes:

1. Material SEE BILL OF MATERIAL
2. No burrs are allowed on the contact area and solder tail area, the maximum allowed stamping burr is 0.05mm unless otherwise.
3. Specification
 Operation Temperature: -40°C to +85°C
 Voltage Rating: 30V AC RMS
 Insulation Resistance: Initial 100MΩ.
 100 MΩ after environment test
 Soldering Heat Resistance: 245
 Durability: 10,000 Cycles
 Mating force : 5N 20N
 Un-mating force: 6N 20N



深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2' X.X' ±0.5'	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: 防水USB TYPE C 24P 沉板 0.4
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW260-USBC24-040B
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-USB2105151612
			SHEET NO. 1 OF 1